

Initial Product/Process Change Notification Document #:IPCN24751Z

Issue Date: 29 Sep 2022

Title of Change:	Qualification of Tanaka 0.8mil Soft PCC wire for TSSOP HSL devices at ASM.	
Proposed Changed Material First Ship Date:	30 Jun 2023 or earlier if approved by customer	
Current Material Last Order Date:	16 Jun 2023 Orders received after the Current Material Last Order Date expiration are to be considered as orders for new changed material as described in this PCN. Orders for current (unchanged) material after this date will be per mutual agreement and current material inventory availability.	
Current Material Last Delivery Date:	29 Jun 2023 The Current Material Last Delivery Date may be subject to change based on build and depletion of the current (unchanged) material inventory	
Product Category:	Active components – Integrated circuits	
Contact information:	Contact your local onsemi Sales Office or <u>Gretel.Ines@onsemi.com</u>	
PCN Samples Contact:	Contact your local onsemi Sales Office to place sample order. Sample requests are to be submitted no later than 45 days after publication of this change notification. Samples delivery timing will be subject to request date, sample quantity and special customer packing/label requirements.	
Additional Reliability Data:	This is an Initial Product/Process Change Notification (IPCN) sent to customers. An IPCN is an advance notification about an upcoming change and contains general information regarding the change details and devices affected. It also contains the preliminary reliability	
Type of Notification:		
Change Category	nge Category	
Category	Type of Change	
Process - Assembly	Change of wire bonding	
escription and Purpose:		

Description and Purpose:

This is Initial Process Chang Notification informing onsemi customers that there will be a change in bond wire for HSL Logic product.

The change is shown below

	Before Change Description	After Change Description
Bond Wire	Heraeus 0.8 mil Bare Copper	Tanaka 0.8 mil Soft PCC

There is no product marking change because of this change.

Reason / Motivation for Change:	Process/Materials Change
Anticipated impact on fit, form, function, reliability, product safety or manufacturability:	The device will be qualified and validated based on the same Product Specification. No anticipated impacts.

TEM001791 Rev. H Page 1 of 2



Initial Product/Process Change Notification

Document #:IPCN24751Z Issue Date:30 Sep 2022

Sites Affected:	es Affected:		
onsemi Sites		External Foundry/Subcon Sites	
onsemi Carmona, Philippines		None	
Marking of Parts/ Traceability of Change:	There will be no change on product marking.		

Reliability Data Summary:

QV DEVICE NAME: NLV74HC74ADTR2G / NLVHC4851ADTR2G

RMS: RMS O84929 / O84927

PACKAGE: TSSOP 16

Test	Specification	Condition	Interval
HTSL	JESD22-A103	Ta= 150°C	2016 hrs
TC	JESD22-A104	Ta= -65°C to +150°C	1000 cyc
HAST	JESD22-A110	130°C, 85% RH, 18.8psig, bias	192 hrs
uHAST	JESD22-A118	130°C, 85% RH, 18.8psig, unbiased	96 hrs
PC	J-STD-020 JESD-A113	MSL 1 @ 260 °C	

Electrical Characteristics Summary:

Electrical characteristics are not impacted.

List of Affected Parts:

Note: Only the standard (off the shelf) part numbers are listed in the parts list. Any custom parts affected by this PCN are shown in the customer specific PCN addendum in the PCN email notification, or on the <u>PCN Customized Portal</u>.

Current Part Number	New Part Number	Qualification Vehicle
NLV74HC74ADTR2G	NA	NLV74HC74ADTR2G / NLVHC4851ADTR2G

TEM001791 Rev. H Page 2 of 2